



Recent Advancements in SiC power devices & the impact of normally-off SiC JFETs on PV inverter platforms

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www.semisouth.com

High MW Electronics – Industry Roadmap Meeting
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SemiSouth Laboratories is a clean energy enabler

specializing in the design & manufacture of silicon carbide (SiC) power devices used to harvest and transfer power in renewable energy systems, telecom server farms & hybrid electric vehicles.

SemiSouth silicon carbide based devices offer higher efficiency, greater power density and higher reliability than comparable silicon-based devices



Solar



Servers



HEV

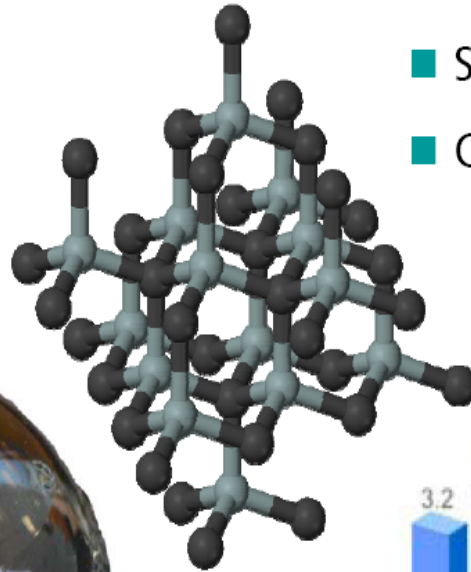


Wind

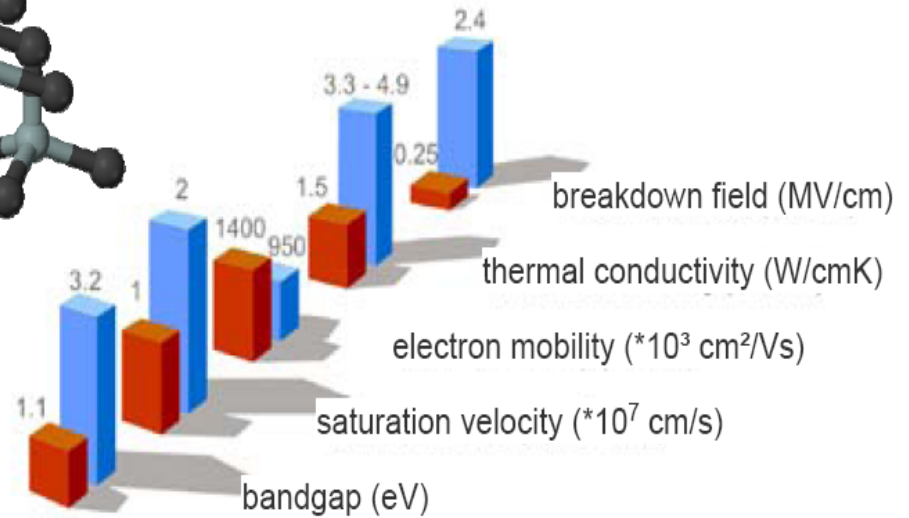


SiC Wafer

World record PV inverter efficiency



- Silicon and Carbon
- Cubic and hexagonal structure (4H)



Silicon Carbide (SiC)

Silicon (Si)

Source: www.wikipedia.de

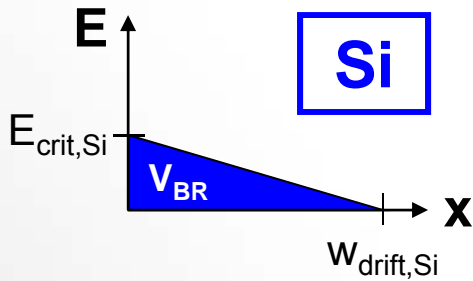
Source: www.siced.de

Material property	Si	4H-SiC	GaN
Bandgap	1.12 eV	3.25 eV	3.4 eV
Breakdown field	0.25 MV/cm	~3 MV/cm	~3 MV/cm
Thermal conductivity	1.5 W/cm•K	4.9 W/cm•K	1.3 W/cm•K
Electron mobility	1200 cm ² /V•s	800 cm ² /V•s	900 cm ² /V•s
Dielectric constant	11.7	9.7	9

- o Silicon carbide is the ideal power semiconductor material
- o Most mature “wide bandgap” power semiconductor material
- o Electrical breakdown strength ~ 10X higher than Si
- o Commercial substrates available since 1991 –
 - ▣ now at 100 mm dia, 150 mm dia soon
- o Defects up to 1,000 times less than GaN
- o Thermal conductivity ~ 3X greater than Si or GaN

unipolar
devices

bipolar (plasma)
devices



$$r_{on} \sim W_{drift} / N_D$$

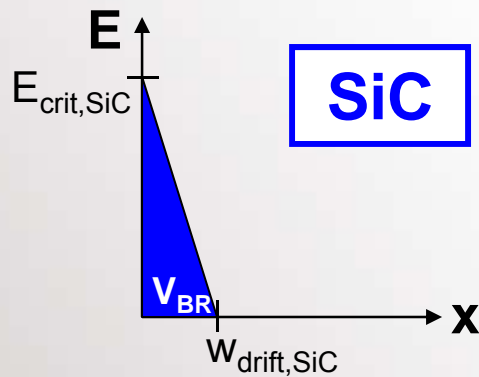
$$q_{st} \sim W_{drift}^2$$

$$E_{crit,SiC} \approx 10 \cdot E_{crit,Si}$$

$$W_{drift,SiC} \approx W_{drift,Si} / 10$$

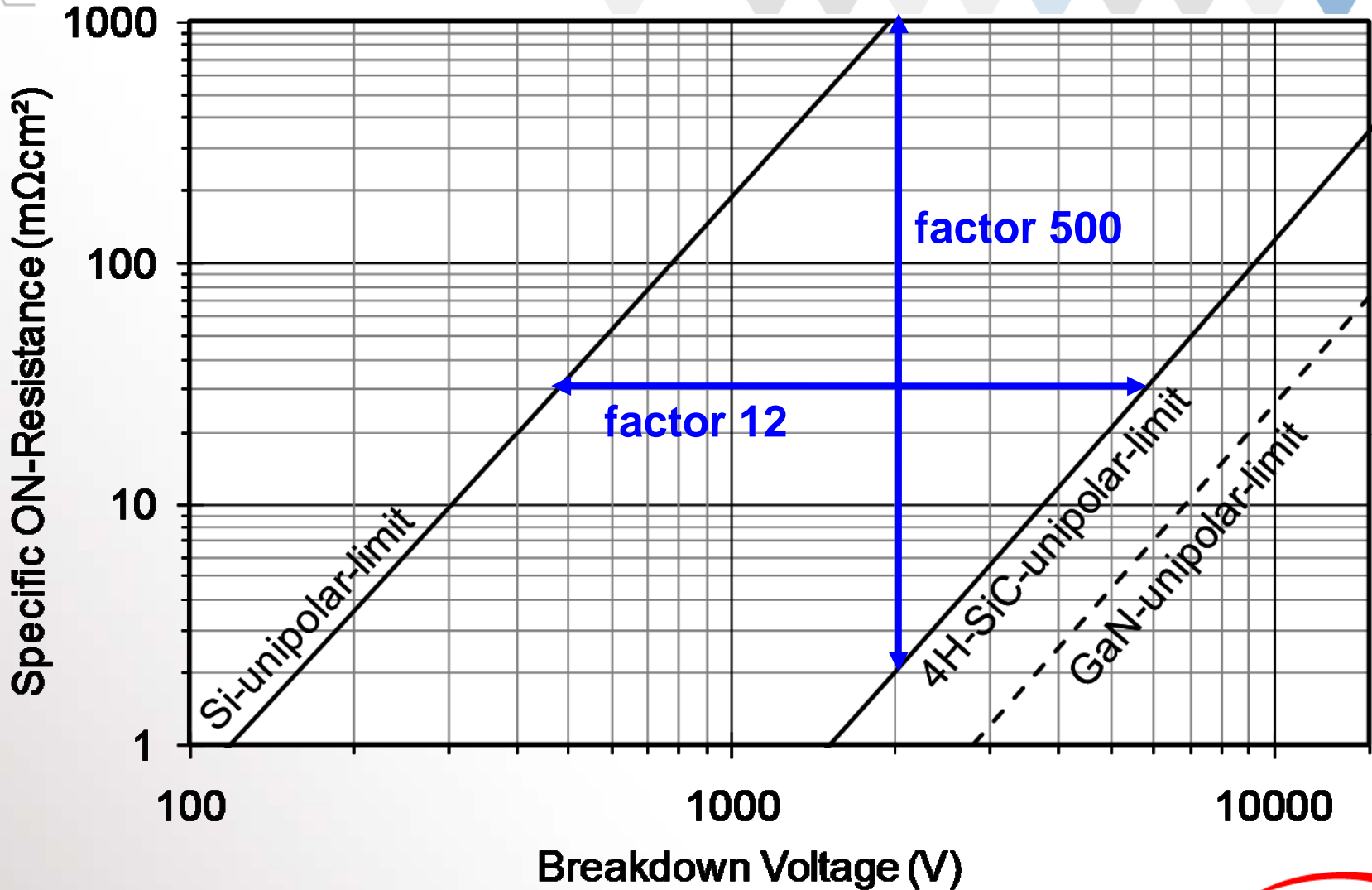
$$W_{drift,SiC} \approx W_{drift,Si} / 10$$

$$N_{D,SiC} \approx 100 \cdot N_{D,Si}$$



$$r_{on,SiC} \approx r_{on,Si} / 1000$$

$$q_{st,SiC} \approx q_{st,Si} / 100$$



- SiC devices can not be 500 times smaller
 - 500 times higher current densities are tough
 - 500 times higher loss densities are deadly (same losses on 500 times smaller area)

- Rather: Design on the same loss density
 - Area and losses reduced by the same factor
 - Benefit would be $\sqrt{\text{BFoM}}$, i.e. still factor 22

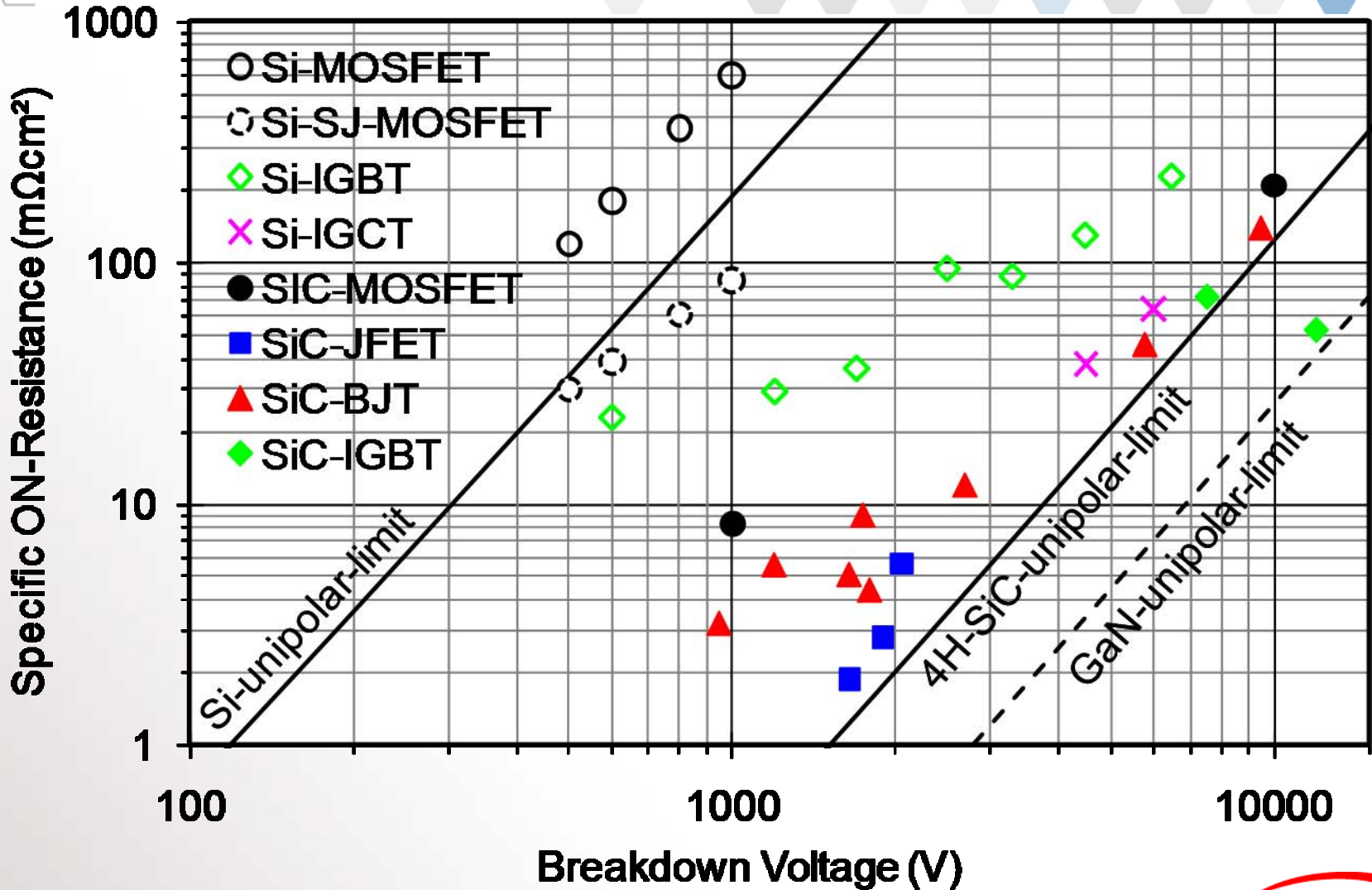
- Note: Threshold voltages do not scale!

Parameter		Silicon	4H-SiC	GaN	Diamond
Band-gap E_g	eV	1.12	3.26	3.39	5.47
Critical Field E_{crit}	MV/cm	0.23	2.2	3.3	5.6
Permittivity ϵ_r	–	11.8	9.7	9.0	5.7
Electron Mobility μ_n	$cm^2/V\cdot s$	1400	950	1500	1800
BFoM: $\epsilon_r \cdot \mu_n \cdot E_{krit}^3$	rel. to Si	1	500	2400	9000
Intrinsic Conc. n_i	cm^{-3}	$1.4 \cdot 10^{10}$	$8.2 \cdot 10^{-9}$	$1.9 \cdot 10^{-10}$	$1 \cdot 10^{-22}$
Thermal Cond. λ	W/cm·K	1.5	3.8	1.3	20

- Low leakage currents (at least theoretically)
- High temperature operation possible (packaging!)
- Better cooling and temperature homogeneity

Functionality	Switches		
Conductivity	Diodes	junction controlled	MOS-controlled
<p>unipolar</p> <p>→ $r_{on} \sim V_{BR}^{2.5}$</p>	<p>[Schottky, JBS]</p>	<p>JFET (✓)</p>	<p>MOSFET ?</p> <p>→ poor & instable interface props.</p>
<p>bipolar (plasma)</p> <p>→ crystal degradation (SiC) low plasma lifetime (GaN)</p> <p>→ $V_T \approx \frac{E_g}{q} - 0.5V$</p>	<p>MPS ✓</p> <p>pin (✓)</p>	<p>BJT (✓)</p> <p>bipolar JFET ?</p> <p>Thyristor</p>	<p>1:1 replacement for Si IGBTs</p> <p>not a real plasma device: high V_T</p> <p>for very high voltages?</p>

SemiSouth *ON-Resistances: State of the Art*

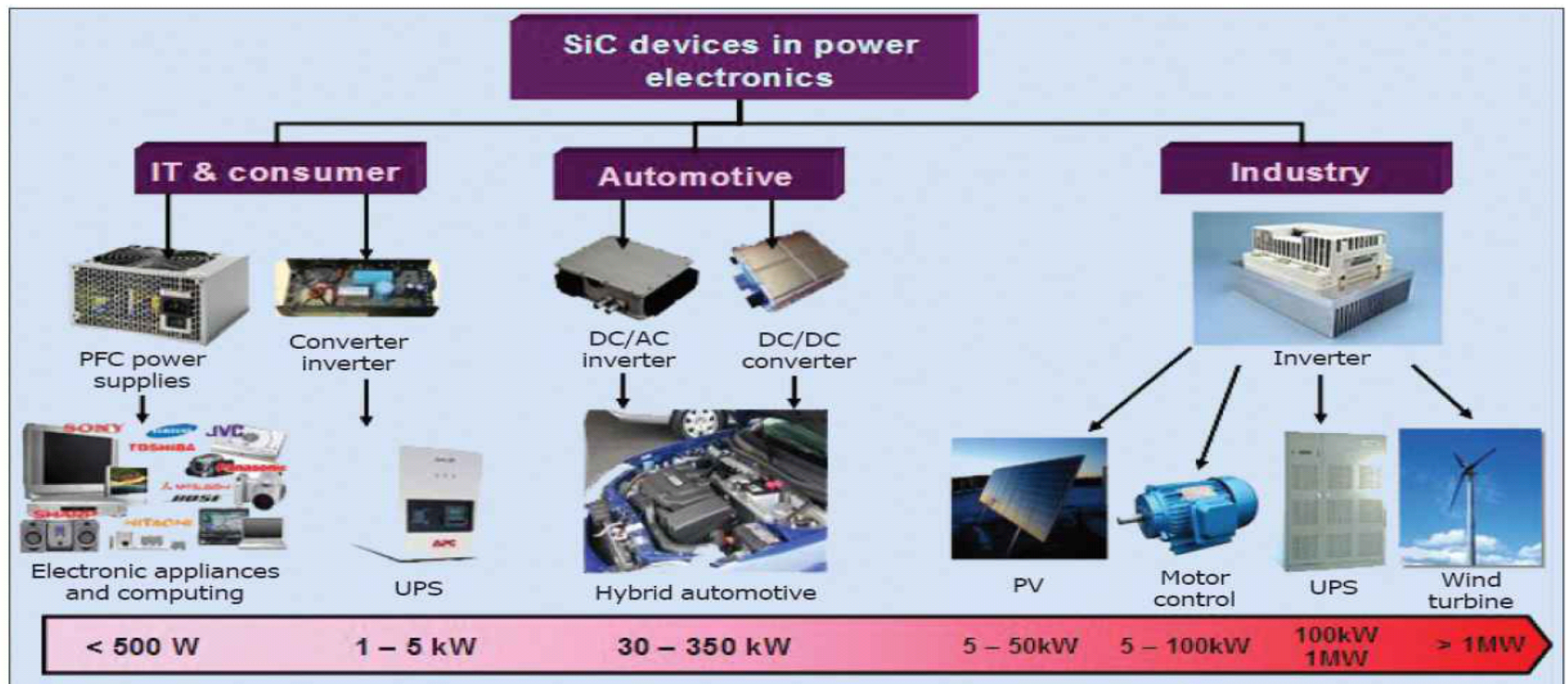


N. Kaminski, EPE2009



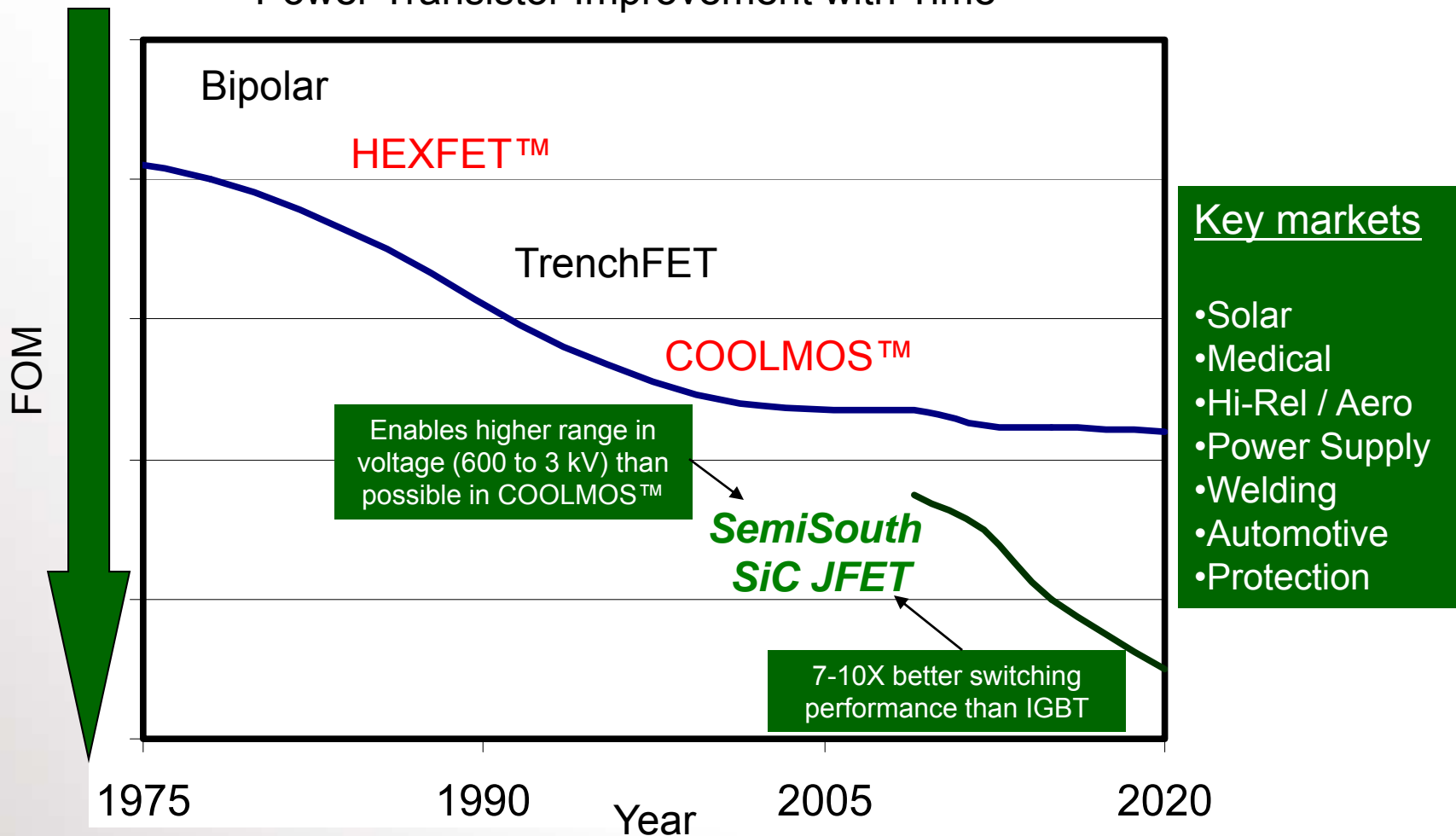
SiC is the Ideal Power Device Technology

*SemiSouth JFETs can Replace IGBTs and MOSFETs for Higher Efficiency and Higher Frequency Switching
Power Dissipation can be reduced by over 50%*





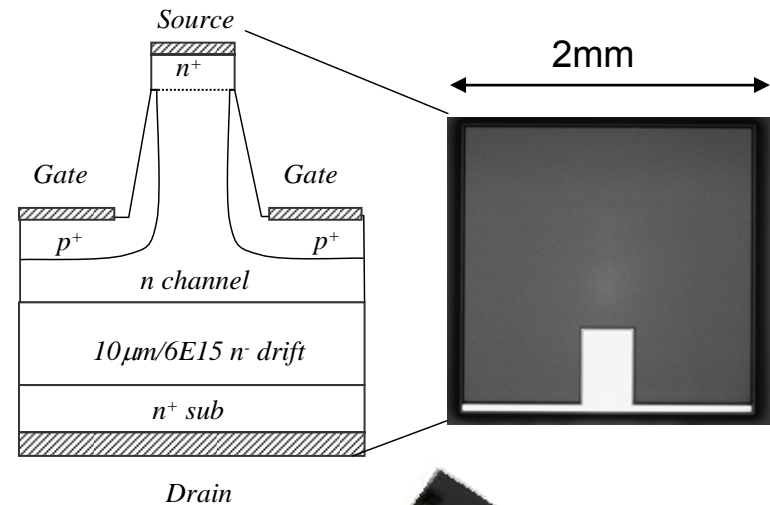
Power Transistor Improvement with Time



SemiSouth JFET advantages

- All benefits of SiC
- Normally-off
- Low process complexity
- No degradation issues (bipolar, MOS, etc.)
- No body diode
- Easily paralleled for high power modules
- Demonstrated stable operation at 350C+
- Lowest $R_{ds(on)}$, sp of EM SiC devices
- fast switching / low switching energy

SemiSouth Vertical-Channel JFET



Fairchild



***NPT IGBT
FGL40N***

***VJFET
SJEP120R063***

***Performance
Improvement***

Critical Parameter

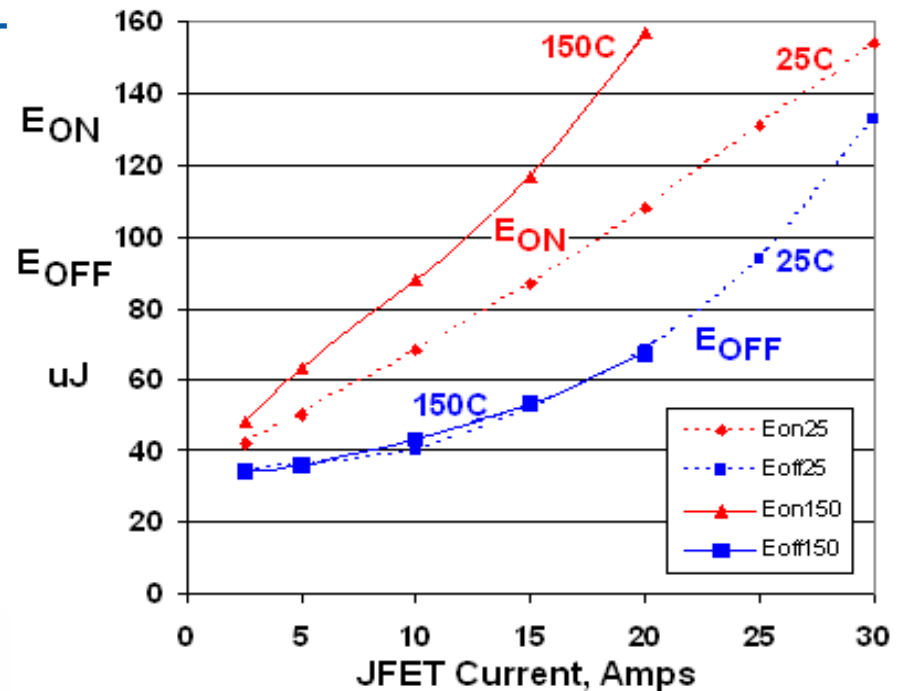
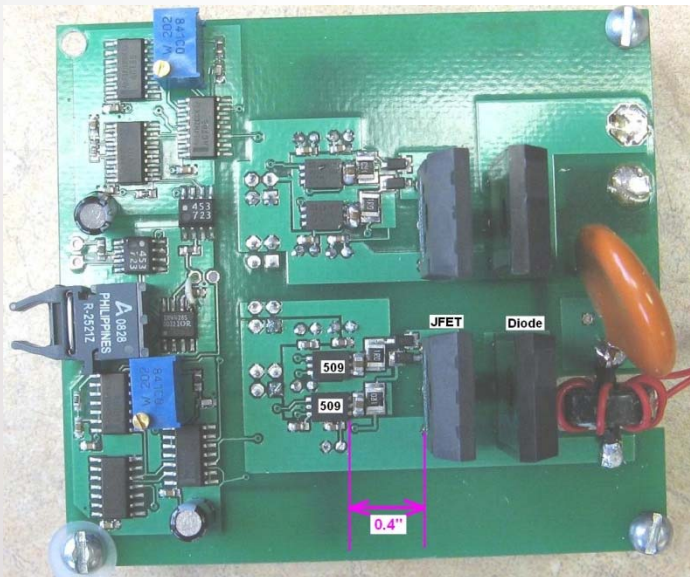
<i>Technology</i>		Silicon – IGBT	Silicon Carbide	
<i>Breakdown Voltage</i>	V_{DS}	1200V	1400V	Higher breakdown margin
<i>On Voltage (conduction)</i>	V_{on}	2.5V	Unipolar	Reduced losses at low I ...higher light load Efficiency
<i>Input Capacitance</i>	C_{iss}	1700 pF.	1220pF	Reduced Gate Power Loss
<i>Effective Output Cap Energy Related</i>	$C_{O(ER)}$	260 pF	100 pF	2.5X Lower Switching Losses
<i>Operating Temperature</i>	T_j	-55°C to 150°C	-55°C to 175°C	Safe Operation at higher Temp
<i>Thermal Impedance</i>	R_{thj-c}	0.25K/W	0.6K/W	X2 worse but offset by overall lower dissipation losses
<i>Turn-On Losses</i>		550uJ	110uJ	
<i>Turn-Off Losses</i>	Joules	1000uJ	70uJ	
<i>Total Losses</i>		1550uJ	180uJ	X10 Lower Switching Energy

SS JFETs HAVE 50% LOWER LOSSES

- Allows high-frequency, high-efficiency, higher power density solutions!

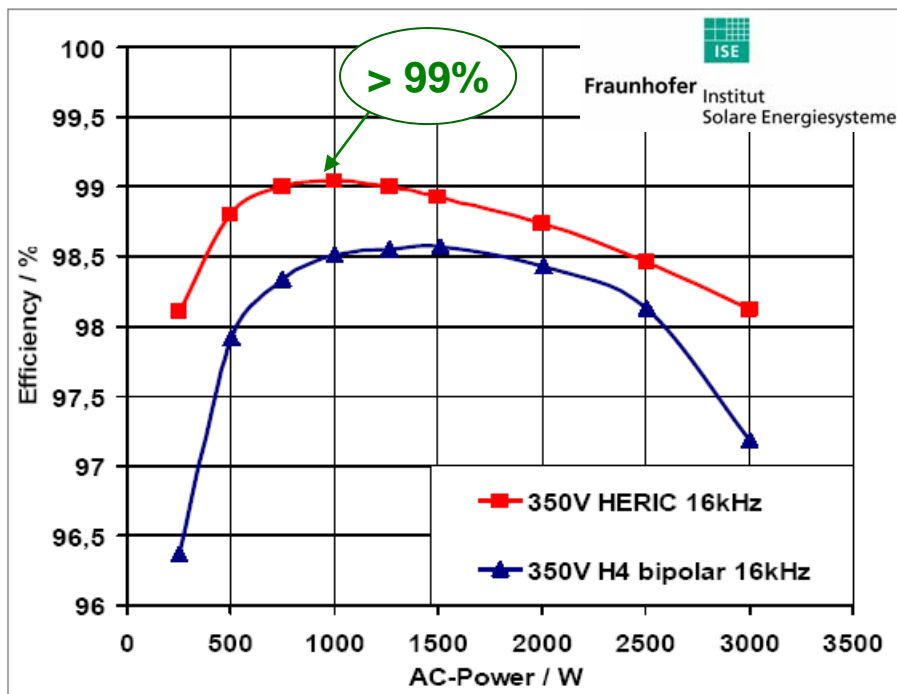
Half-Bridge Configuration:

- **SJEP120R063: 1200V / 63mΩ VJFET**
- **SDP20S120: 1200V / 20A SBD**

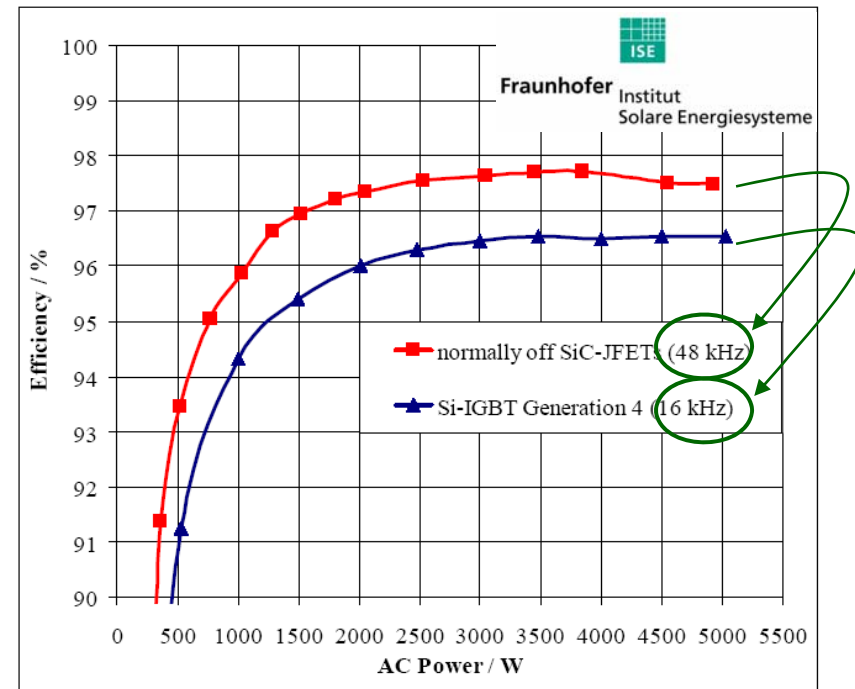


“We now use junction field-effect transistors (JFETs) made of silicon carbide (SiC) manufactured by SemiSouth Laboratories Inc.. This is the main reason for the improvement”, - Prof. Bruno Burger, leader of the Power Electronics Group at Fraunhofer ISE, July 2009 press release.

- Single phase Heric®
- Commercial inverters @ 98%
- SemiSouth’s JFET lowers losses ~ 50%



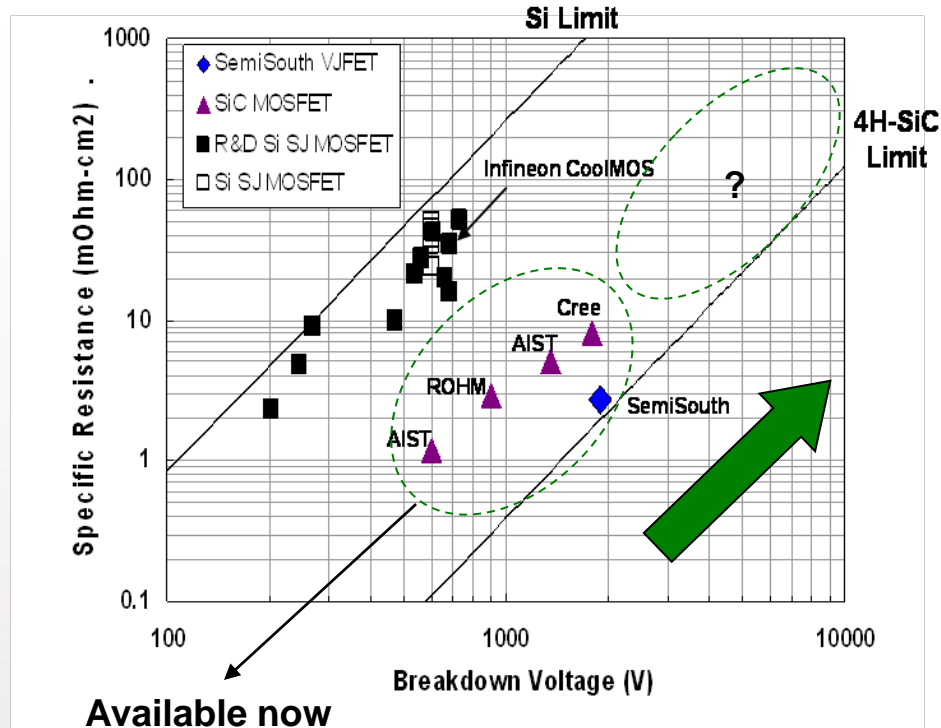
- Three phase full bridge inverter
- SemiSouth JFET *boosts efficiency 1.2%*
- SemiSouth JFET operates *3X higher freq.*

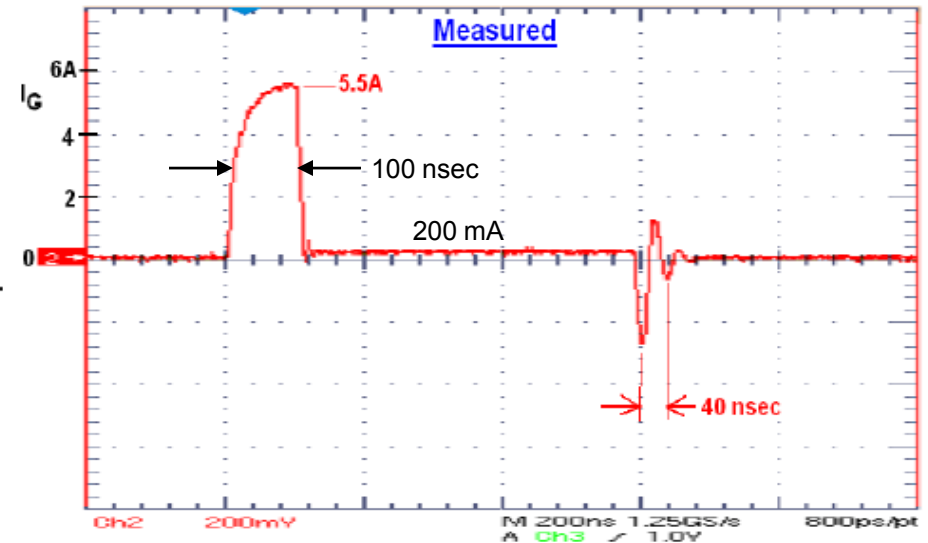
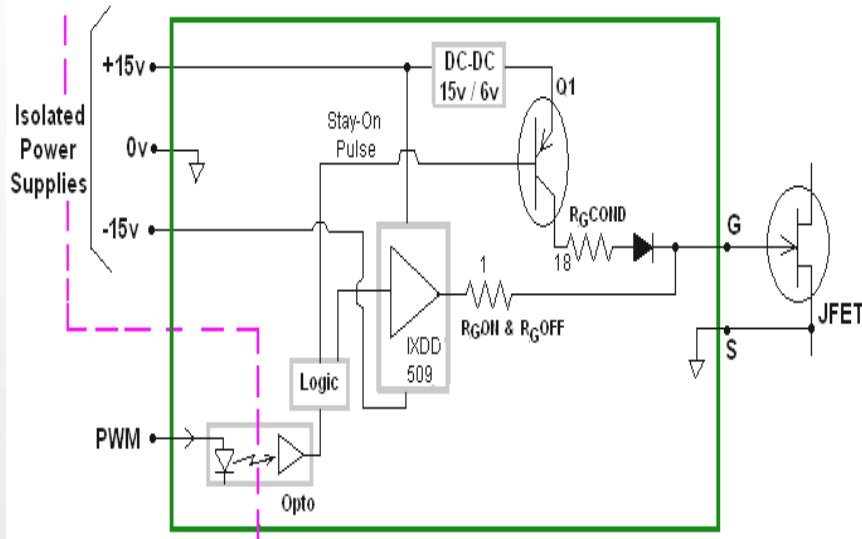


* Bruno Burger, Dirk Kranzer, “Extreme High Efficiency PV-Power Converters,” EPE, Barcelona, Spain, 8-10 September 2009

Trench JFET Technology Evolution:

- Initial demonstration in 2007
- Compact design leads to ultra-low specific on-resistance
- Initial product release in 2008





Opto Coupler: This reference design uses the HP “wide body” HCHW4503 high speed opto coupler enabling fast switching speeds while allowing layout spacing to meet safety isolation requirements.

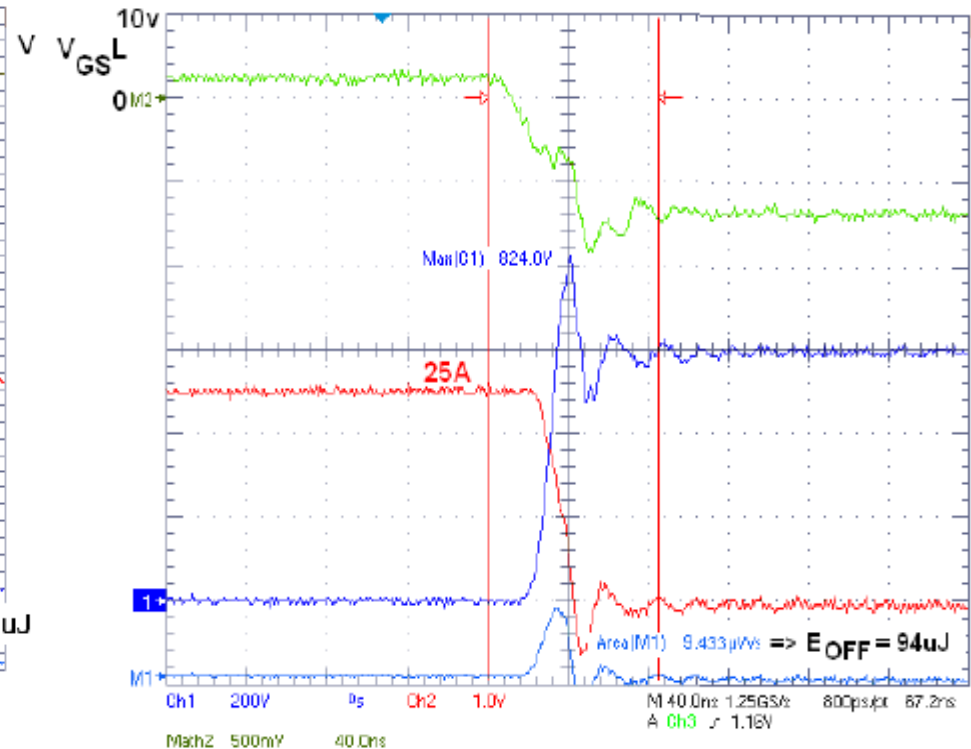
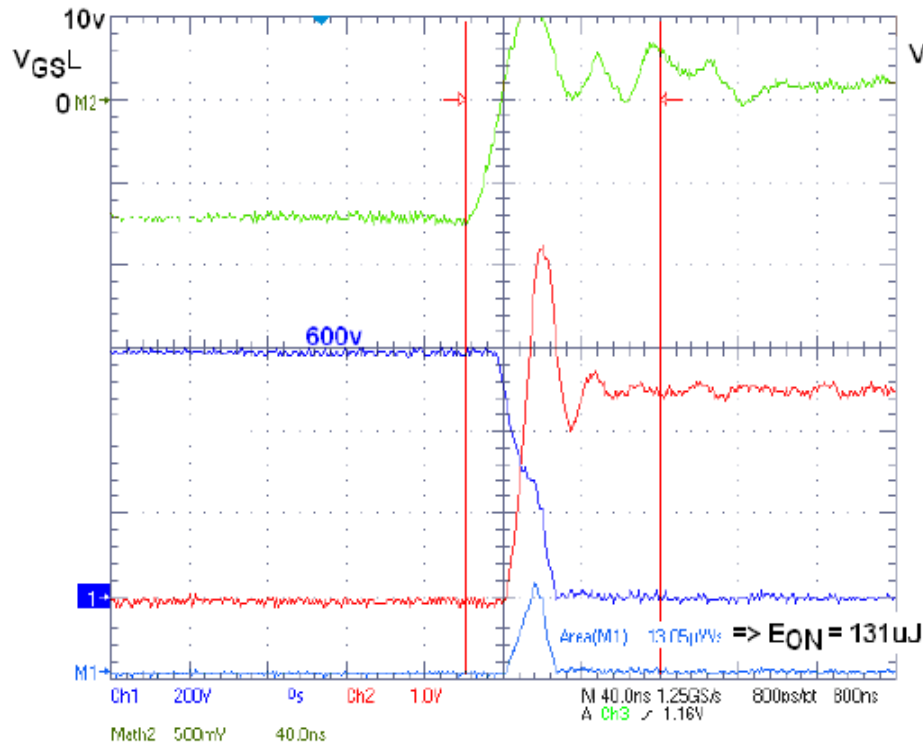
509 Gate Driver: The IXYS IXDD509 high speed Driver is used to provide a high current Turn-on and Turn-off gate pulse through $R_{g(on/off)}$ for very fast switching and low switching losses.

Q1 Conduction Driver: Q1 is a small PNP transistor used to provide the ON-state gate current of 200mA to maintain a low $R_{ds(on)}$ in the SJEP120R063 or 050 JFET during the conduction period.

15V to 6V DCDC: This step down (85% eff) DCDC converter IC is used as the power source for Q1 and enables a reduction in gate power loss during the conduction period. (optional).

Timing Logic: The logic / timing circuit generates the required timing signal for the IXDD509 gate Driver and Q1. The timing is set to achieve a 100nsec turn on high I pulse and then maintain the 200mA conduction pulse.

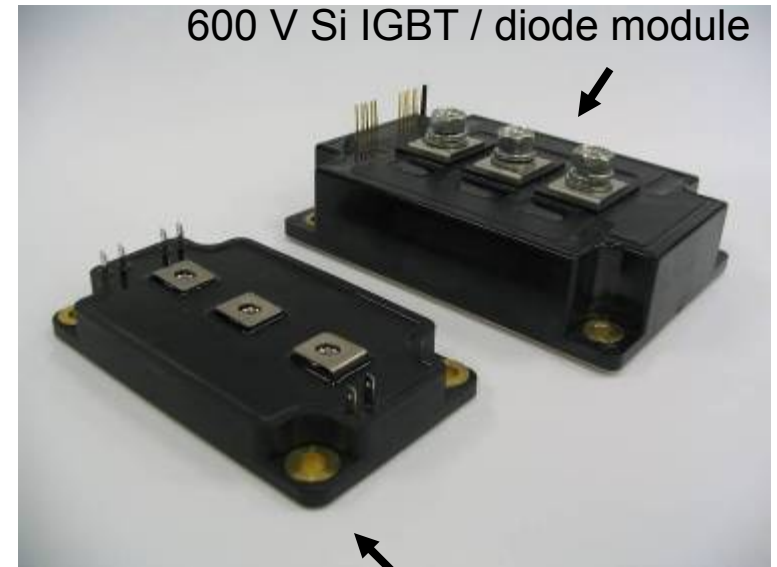
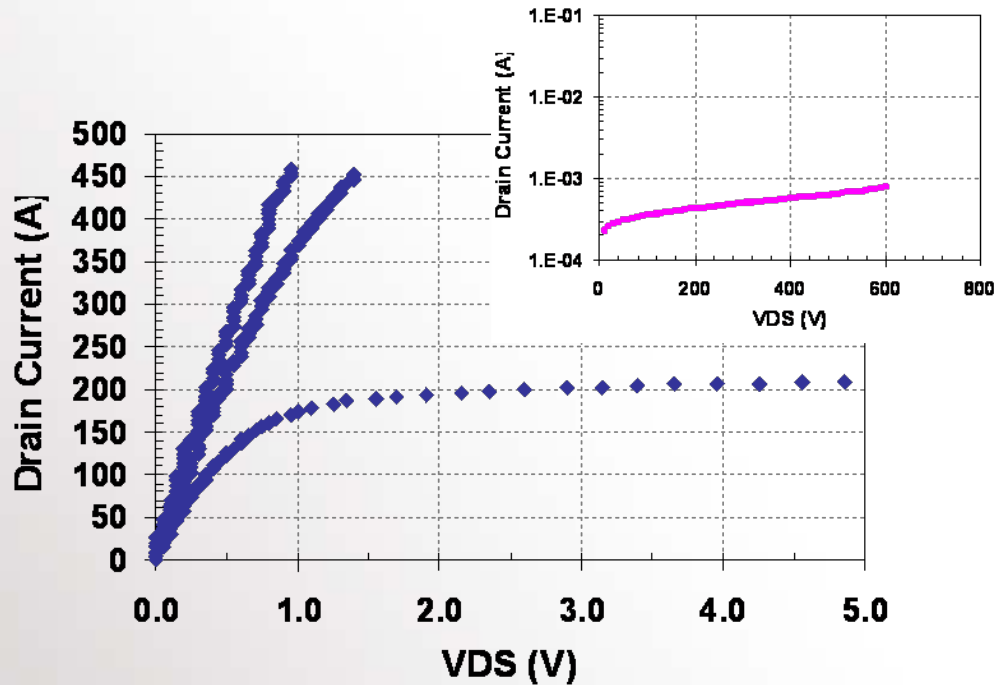
25A and 600V



Comments:

1. These switching losses are in line with the data sheet and the higher temperature (150C) switching losses would be similar to the data sheet as well and only 10% higher.

- 600 V / 450 A SiC Normally-off JFET module
- Up to 57% reduction in conduction losses possible at 1200 V level ($\sim 2.2\text{m}\Omega$ @ 1V)

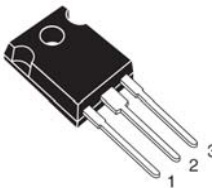
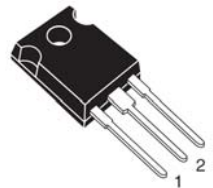
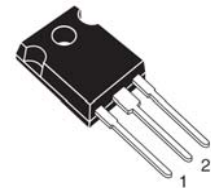
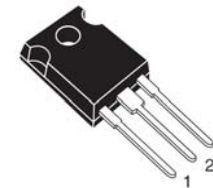
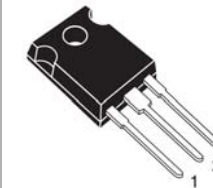



1200 V SiC JFET / diode module
(SemiSouth enhancement-mode JFET)

Improved "125" to "100"

Dual Die

Products Released in Sept 2008

Part	SJEP120R125	SJEP120R100	SJEP120R063	SJEP120R050	SJEP120R025	SJEP170R550
Package	 3L TO-247	 3L TO-247	 3L TO-247	 3L TO-247	 3L TO-247	 3L TO-247
Voltage (V)	1200	1200	1200	1200	1200	1700
Rds(on)	125 mΩ	100 mΩ	63 mΩ	50 mΩ	25 mΩ	550 mΩ
Ciss Tr*/Tf* (ns) Die size	576 pF 50 /50 4 mm ²	TBD TBD 4.5 mm ²	2 x 576 pF 50 /50 2 x 4 mm ²	1168 pF 50 /50 9 mm ²	2320 pF 50 /50 15 mm ²	167 pF 50 /50 2 mm ²
Co-Pak Options	5A SBD Q2 09	5A SBD TBD	-	10A SBD Q3 09	-	-
Samples	Now	Now	Now	Q3 09	Q1 10	Q2 09
Production	Now	Now	Now	Q4 09	Q2 10	Q4 09

Latest Datasheets at <http://www.semisouth.com/products/powersemi.html>

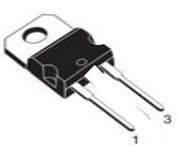

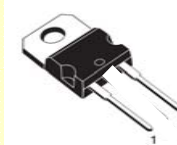
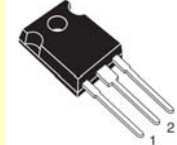

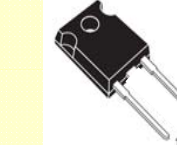



Accepting Sample and Production orders



30-50 ns typical

UPDATED 11 Aug 2009

Part	SDA05S120	SDP10S120D	SDA10S120	SDP20S120D	SDA30S120	SDP30S120
Package	 2L TO-220	 3L TO-247	 2L TO-220	 3L TO-247	 2L TO-220	 2L TO-247
BV (V)	1200	1200	1200	1200	1200	1200
I _F (A)	5A	10A (2 x 5A)	10A	20A (2 x 10A)	30A	30A
V _{Fmin} (V)	1.6	1.6	1.6	1.6	1.6	1.6
V _{Fmax} (V)	1.8	1.8	1.8	1.8	1.8	1.8
Samples	Now	Q1 09	Now	Now	Q3 09	Now
Production	Q2 09	Q2 09	Now	Now	Q4 09	Q2 09

 Accepting Sample and Production orders

- ***SiC is maturing, cost declining***
 - ▣ ***100 mm dia wafers now; 150 mm dia wafers soon***
 - ▣ ***SiC FET devices suitable up to 3-4 kV, and being released now***
 - ▣ ***SiC bipolar (BJT, IGBT, ...) for > 3 kV still being developed***
 - ▣ ***MOS controlled devices still challenging***

- **Released first normally-off SiC JFET in 2008**
 - ▣ **High reliability, easily paralleled for high power modules**
 - ▣ **Small die + High Performance + Low process complexity**
 - ▣ ***Low \$ for SiC level performance expectations***

- ***World record (> 99%) PV inverter efficiency***
- ***Enables higher power density inverters***

